







WG4 – Progress report

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Outline

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Upgrade requirements:

Parameters: Option 1

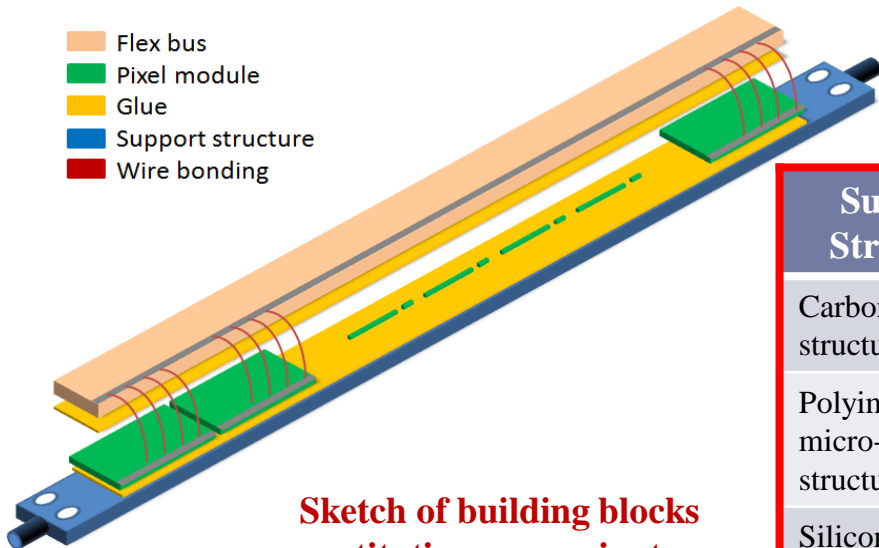
Beam pipe radius	mm	20 (outer radius)
Number of pixel layers		3
Mean radial positions	mm	22, 47, 90
Stave length	mm	210, 270, 370
Power consumption	W/cm ²	0.3 – 0.5
Total material budget per layer	X/X ₀ (%)	≤ 0.5
Working temperature	°C	≤ 35
Temperature gradient	°C	≤ 5
Maximum deformation	μm	Few microns

Parameters: Option 2

Parameters: Option 2		Pixel	Pixel – strip
Number of pixel layers		3	4
Mean radial positions	mm	22, 38, 68	124, 235, 396, 430
Stave length	mm	210, 250, 320	450, 670, 1070, 1140
Power consumption	W/cm ²	0.3 – 0.5	
Total material budget per layer	X/X ₀ (%)	≤ 0.5	≤ 1
Working temperature	°C	≤ 35	
Temperature gradient	°C	≤ 5	
Maximum deformation	μm	Few microns	

Stave material budget

Component	Material budget X/X0 (%)	Notes
Support Structure	0.07 – 0.34	3 different structures are under discussion: carbon foam, polyimide and silicon
Glue	0.045	2 layers of glue 100 μm thick each
Pixel module	0.053 – 0.16	Monolythic (50 μm thick) – hybrid (150 μm thick)
Flex bus	1.5	Reasonable value if a singel layer flex bus is considered
Total	0.32 – 0.7	

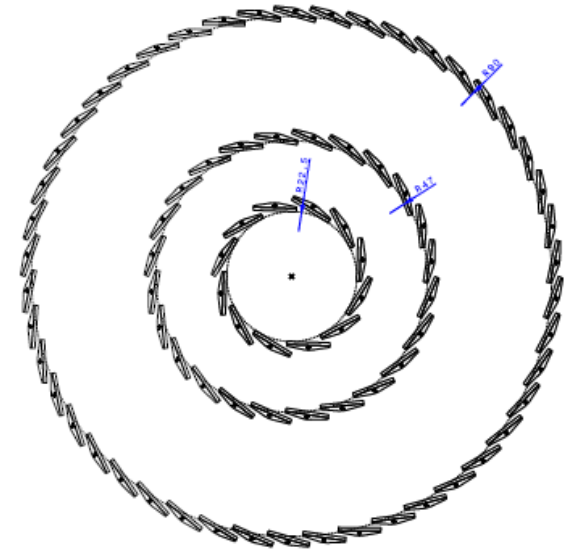
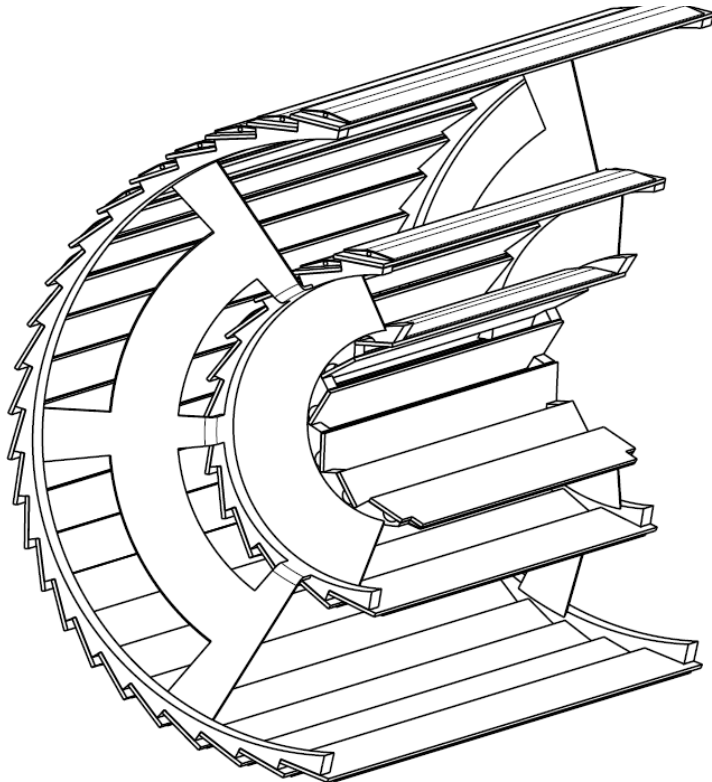


Sketch of building blocks constituting a generic stave

Support Structure	Material budget X/X0 (%)	Notes
Carbon foam structure	0.22 – 0.34	Different cooling tubes: PEEK or Metal (MP35N)
Polyimide micro-channel structure	0.085 – 0.13	Different coolant: H2O or C6F14
Silicon micro-channel structure	0.07 – 0.11	Different layout: sideline or distributed micro-channels

Conceptual Design: Option 1

- ▶ 3 layers of SI-pixel sensors: 1st layer at 23 mm from the IP
- ▶ Full structure divided in 2 half, to be mounted around the beam pipe and to be moved along the beam pipe towards the final position
- ▶ Modules fixed to the 2 carbon fiber wheels
- ▶ All the services on side A
- ▶ Number of staves per layer: 12, 24, 46

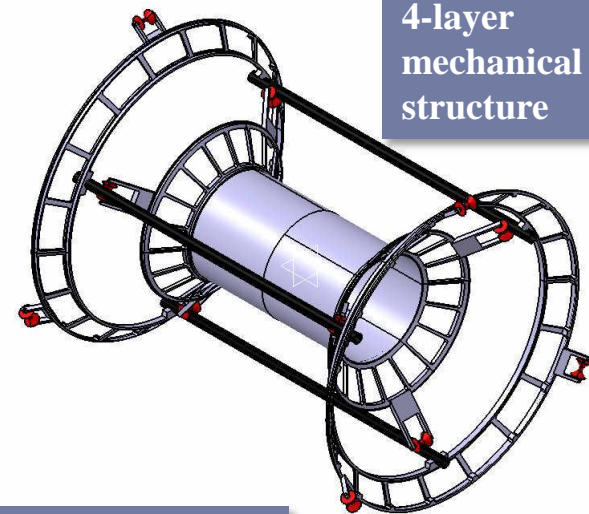


Constraints:

- ▶ Stave 15mm wide
- ▶ 2 mm dead area on one side
- ▶ Full azimuthally coverage
- ▶ Closest point to the beam pipe: 22.5mm (2 mm of clearance)
- ▶ 2 mm of clearance between neighboring staves

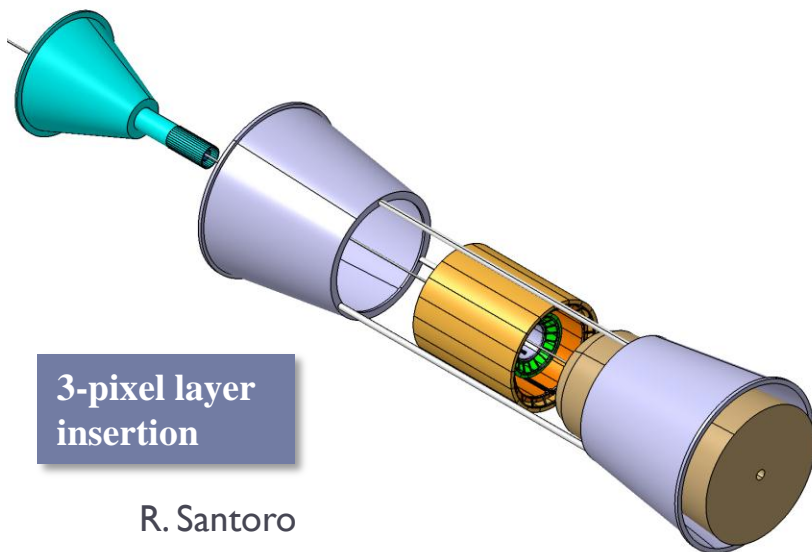
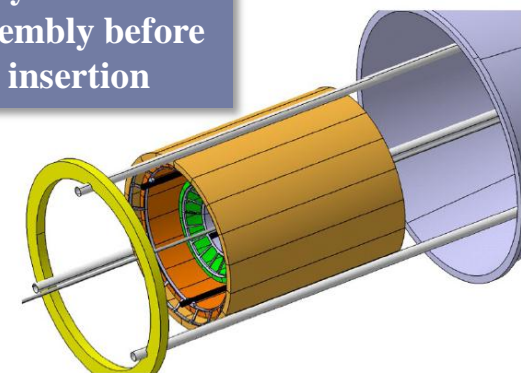
Conceptual Design: Option 2

- ▶ 3-pixel layers are based on the same structure shown before
- ▶ 4 strip layers, based on 2 separate barrels, each one supporting two detector layers
- ▶ Three tubes in carbon composite or beryllium are permanently fixed between the 2 barrels both to rigidify the structure and to support - guide the inner barrel insertion
- ▶ Three tubes in carbon composite or beryllium are permanently fixed in the inner surface of the TPC to support - guide the 4layer barrel insertion
- ▶ 4-layer structure mounted outside the TPC before it is moved in the final position
- ▶ The 3-pixel layer insertion has to be studied



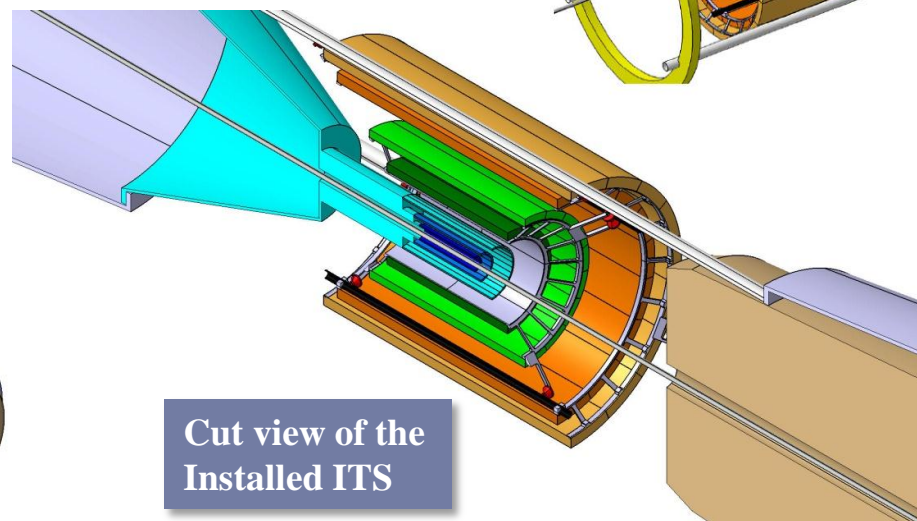
4-layer mechanical structure

4-layer assembly before the insertion



3-pixel layer insertion

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Cut view of the Installed ITS

Air cooling

Preliminary considerations on air cooling, based on simplified calculation

Assumptions

- ▶ Air flowing along the tubes with no air leakage
- ▶ 3 cylinders with the pixel structure dimension
- ▶ Power uniformly distributed along the surfaces (0.3 or 0.5 W/cm²)
- ▶ Air inlet 7°C and sensor limit = 35°C

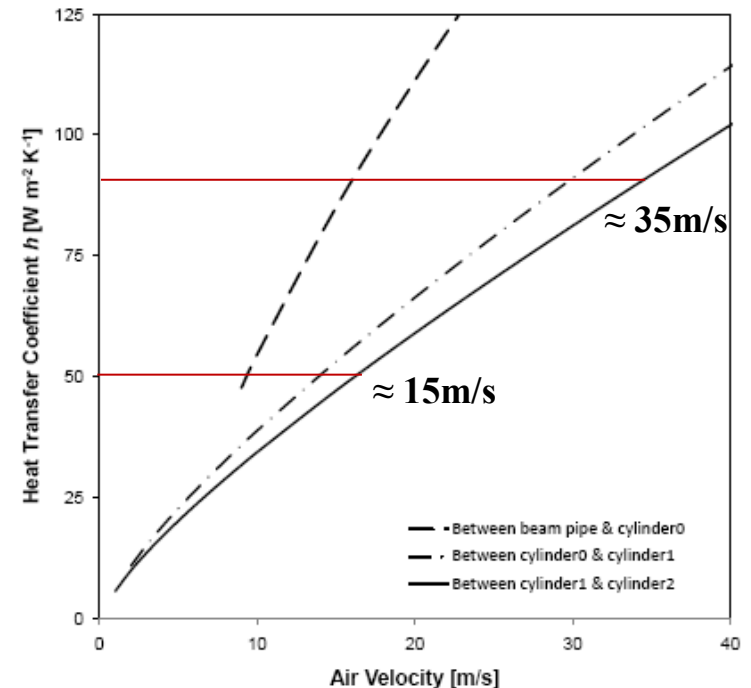
Considerations

- ▶ Those are only preliminary studies which show that we need very low power consumption to cool down the detector with reasonable air flow (less than 10 m/s)
 - ▶ Simulations could be started if power consumption lower than 0.3 W/cm² is feasible
 - ▶ STAR uses ≈10m/s with a power consumption of ≈0.17 W/cm²
- ▶ If air cooling will be considered, the mechanic design should be similar to the actual mechanics
- ▶ The services needed to force the air could add material budget at forward rapidity on A side

$$q/2 = h(T_s - T_a)$$

$$q = 0.3\text{W}/\text{cm}^2 \Rightarrow h \approx 50\text{Wm}^{-2}\text{K}^{-1}$$

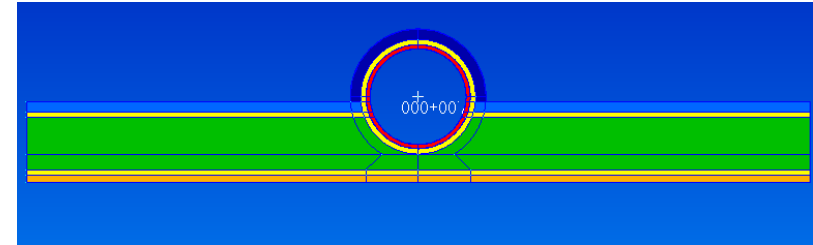
$$q = 0.5\text{W}/\text{cm}^2 \Rightarrow h \approx 90\text{Wm}^{-2}\text{K}^{-1}$$



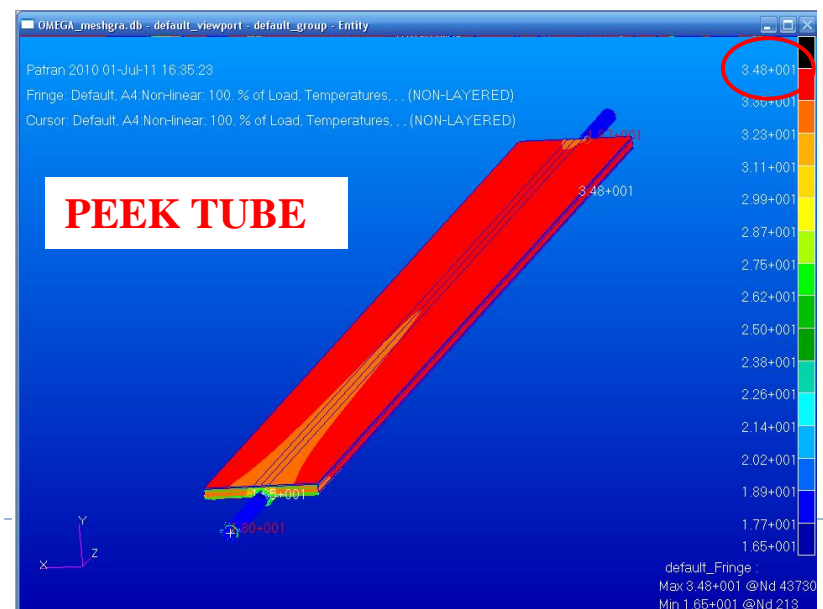
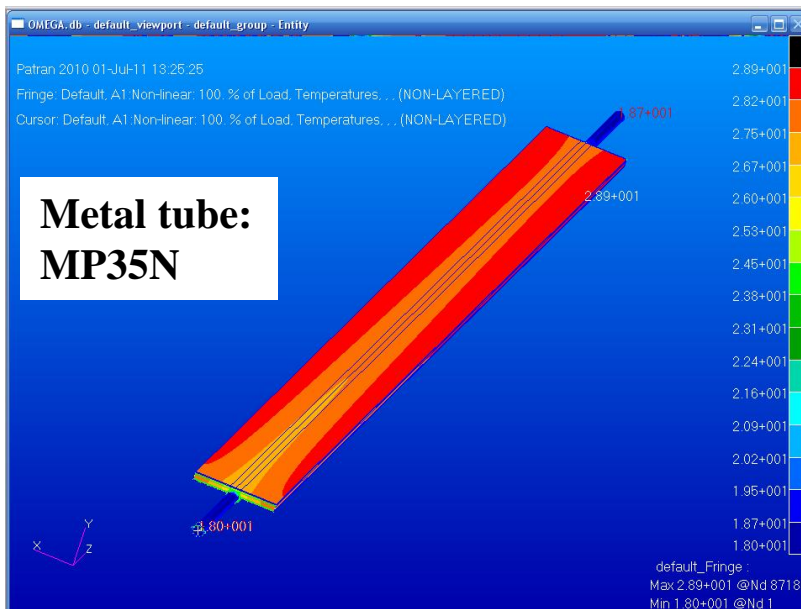
Carbon foam structure

Preliminary simulations with reasonable values of material conductivity and thickness.
In these studies we assume surfaces with ideal contact

- ▶ Power consumption 0.5 W/cm²
- ▶ Cooling with water in leakless
- ▶ Inlet temperature = 18°C and flow rate 0.3 lit/min
- ▶ Glue conductivity 1 W/mK (100µm thick)
- ▶ Carbon foam conductivity 50 W/mK (1mm thick)



- ▶ **Glue**
- ▶ **Tube 2mm diameter ext and wall 80µm thick**
- ▶ **Omega in carbon fiber**
- ▶ **Carbon foam**
- ▶ **Silicon detector**

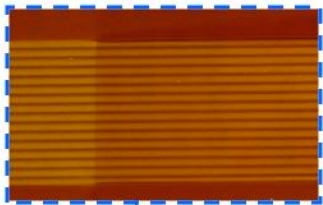


Polyimide micro-channel

Fabrication process

- ▶ Starting point: 1 layer of LF110 (50 μm thick) and 1 layer of PC1020 (50 μm thick)
- ▶ Grooves obtained with photolithography
- ▶ Cover lay hot pressed on the top and final cure @ 180°C for 10 Hours

Simulation and tests on prototype based on micro-channels 200 x 800 μm^2

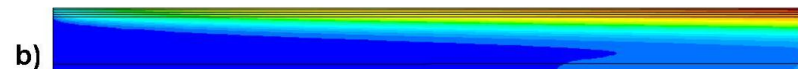
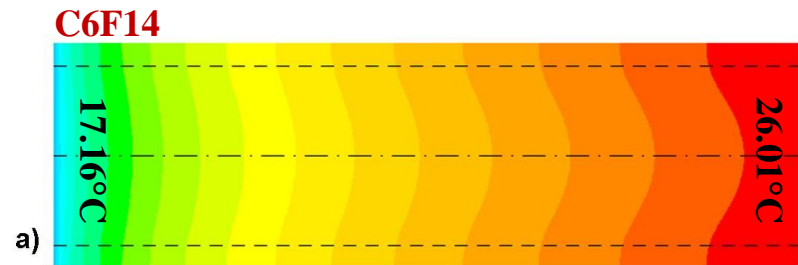
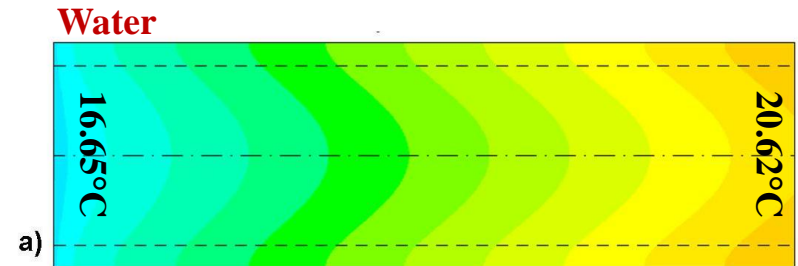
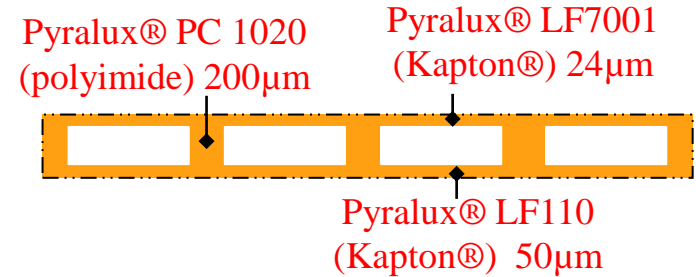


Tests on prototypes:

- ▶ Leak test and water compatibility (ok)
- ▶ Thermo fluid dynamic test (soon)
- ▶ Mechanical test (soon)



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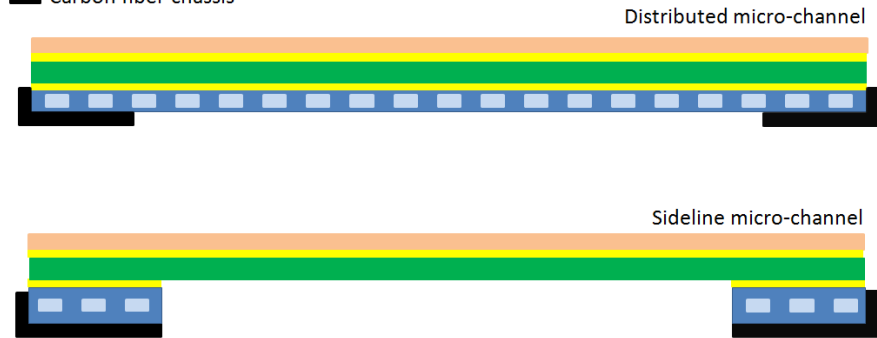


Simulated temperature distribution: polyimide surface and side view with 0.5 W/cm²

Si-Micro-channel

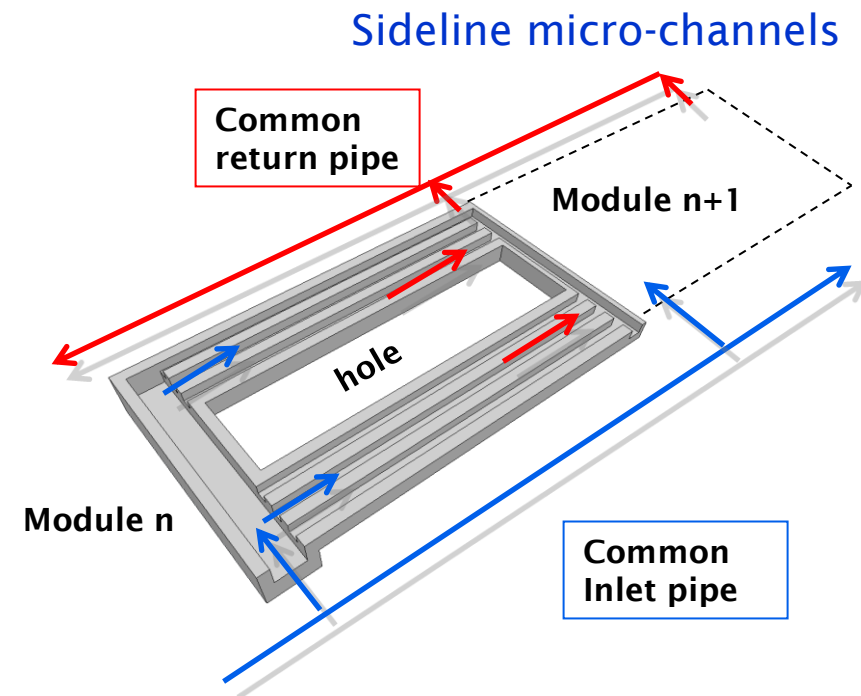
- ▶ Micro-channels made on etched silicon plates covered with Si-plate by fusion bonding
- ▶ Two layouts are under discussion
 - ▶ **Distributed micro-channels:** material budget equally distributed below the sensitive area
 - ▶ **Sideline micro-channels:** micro-channels confined at the chip's border

- Flex bus
- Pixel module
- Glue
- Silicon micro-channel support
- Micro-channels 100 x 200 μm
- Carbon fiber chassis

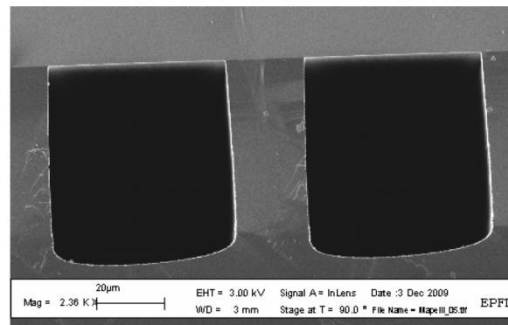


Further considerations

- ▶ This is actually an option considered for the NA62 Experiment at CERN
- ▶ Suitable with double-phases cooling (CO2 or fluorocarbons)
 - ▶ Simulation and R&D are needed
- ▶ Limitation: the standard process is actually 4" wafer although CEA-LETI is trying to manufacture 8" silicon wafer

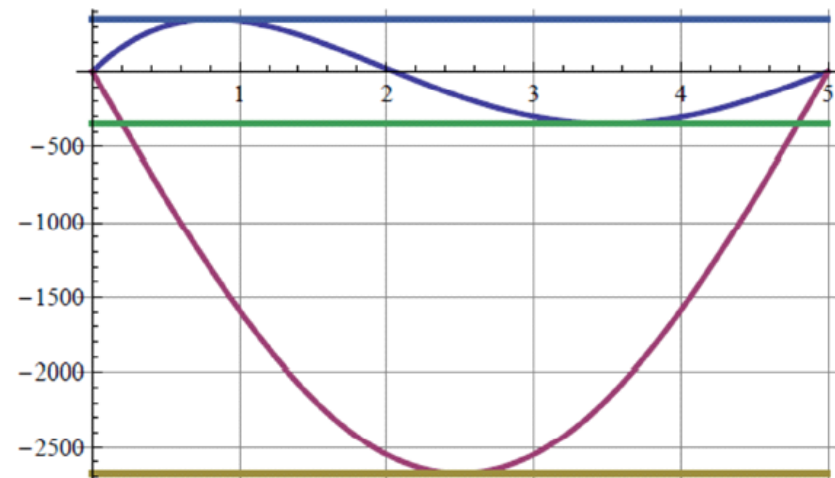
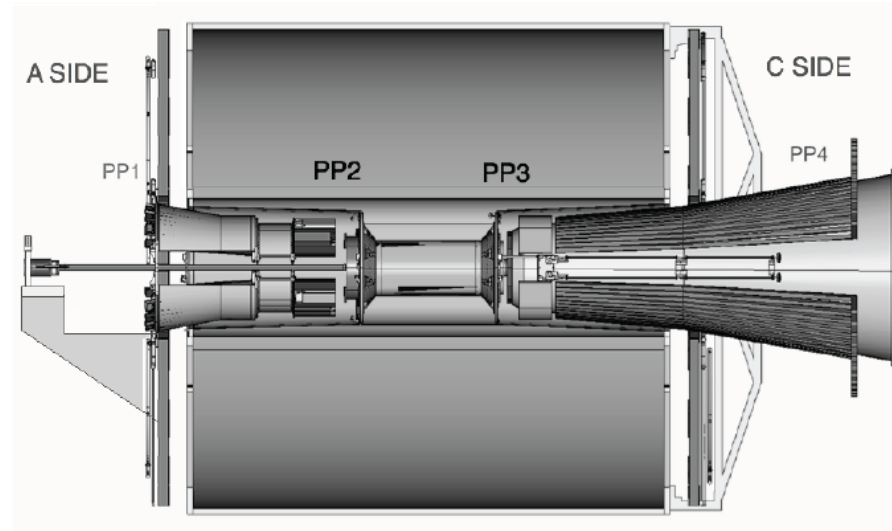


Cross section image of silicon microchannels 200 x 200 μm^2



Beam pipe considerations

- ▶ The beampipe is actually hold in 3 points (FMD2, FMD3 and service support wheels)
- ▶ To permit the insertion of the ITS from the A side, the central support has to be removed
- ▶ The sagitta of a beampipe 5m long with the wall 800 μ m thick has been studied
 - ▶ The sagitta can be reduced applying a moment along the beam axis on one end (8Nm)
 - ▶ Almost the same result has been calculated with a thinner wall (500 μ m)
- ▶ Discussions to have a beam pipe with the inner radius of about 19mm are on-going
- ▶ Beam pipe with 500 μ m wall seems to be feasible although R&D is needed
 - ▶ The worry is the “porosity” and the vacuum tightness
 - ▶ Prototypes are needed



Spare
